

Freescale Semiconductor Reference Manual Addendum

MCF5373RMAD Rev. 1.3, 05/2007

MCF5373 Reference Manual Errata

by: Microcontroller Division

This errata document describes corrections to the *MCF5373 Reference Manual*, order number MCF5373RM. For convenience, the addenda items are grouped by revision. Please check our website at http://www.freescale.com/coldfire for the latest updates.

The current version available of the *MCF5373 Reference Manual* is Revision 1.

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1 Errata for Revision 1

Table 1. MCF5373RM Rev 1 Errata

Location	Description
Table 2-1/Page 2-2	Change D[31:0] signal direction from output (O) to input/output (I/O).
Table 2-16/Page 2-17	Change USBOTG_PU_EN to an output and change the description to the following: Enables an external pull-up on the USBOTG_DP line. This signal is controlled by the UOCSR[BVLD] bit.
Table 3-1/Page 3-5	Change PC's Reset Value entry to "Contents of Location 0x0000_0004" and Written with MOVEC entry to "No". Change OTHER_A7's Reset Value entry to "Contents of Location 0x0000_0000".
Figure 3-5/Page 3-7	Change "Access: User read-only" to "Access: read/write". Change CCR[4:0] to read/write.
Table 3-2/Page 3-8	Remove last sentence in C bit field description.
Figure 3-8/Page 3-9	Change SR[4:0] to read/write.
Section 3.4/Page 3-11	Change last bullet to "Use of separate system stack pointers for user and supervisor modes"
Section 3.4/Page 3-11	Change last sentence in step #2 to "The IACK cycle is mapped to special locations within the interrupt controller's address space with the interrupt level encoded in the address."
Section 3.4/Page 3-11	Delete second and third sentences in step #3. Delete the clause "For processorspointers" from the fourth sentence in step #3.
Figure 4-4/Page 4-5	Change MACSR[3:0] to R/W.
Figure 4-5/Page 4-10	Change upper 16 bits of the MASK register to read-only, with a read and reset value of 1.
Equation 4-3/Page 4-13	Add minus sign to the exponent so that it is " $-(i + 1 - N)$ ".
Table 5-2/Page 5-4	Change reset value of ACR0, ACR1 to "See Section" since some of the bits are defined after reset.
Section 5.3.2/Page 5-6	Add the following note:
	NOTE Peripheral space (0xE000_0000-0xFFFF_FFF) should not be cached. The combination of the CACR defaults and the two ACRn registers must define the non-cacheable attribute for this address space.
Section 5.4.6/Page 5-14	Change first sentence from "Ways 0 and 1 of the data cache can be locked by setting CACR[DHLCK]; likewise, ways 0 and 1 of the instruction cache can be locked by setting CACR[IHLCK]." to ""Ways 0 and 1 of the cache can be locked by setting CACR[HLCK]."
Figure 5-8/Page 5-15	Change sentence near top of figure from "B) CACR[DHLCK] is set, locking ways 0 and 1." to "B) CACR[HLCK] is set, locking ways 0 and 1."
Table 8-9/Page 8-8	Added the following note to the LPCR[FWKUP] (fast wake-up) bit description: Note: Setting this bit is potentially dangerous and unreliable. The system may behave unpredictably when using an unlocked clock, since the clock frequency could overshoot the maximum frequency of the device.
Section 9.3.5/Page 9-6	The CDR[SSIDIV] field is a 6-bit field. Expand the field in the figure and bit description table from bits 3–0 to bits 5–0
Section 11.2.8/Page 11-10	Combine all BCR[7:0] fields into a single slave burst enable field, SBE. The only valid values for this field are 0x00 and 0xFF. All other values are reserved.



Location	Description
Table 13-1/Page 13-4	Change D[31:0] signal direction from output (O) to input/output (I/O).
Section 17.4.4 & 17.4.5	In figure 17-8 through figure 17-33 add 'ADDR[31:0]' label to first cycle of data signals.
Section 17.4.4.1/Page 17-12	Change last note on page from "The processor drives the data lines during the first clock cycle of the transfer. However, this should be ignored by the connected device." to: "The processor drives the data lines during the first clock cycle of the transfer with the full 32-bit address. This may be ignored by standard connected devices using non-multiplexed address and data buses. However, some applications may find this feature beneficial."
Figure 17-27/Page 17-24	Remove internal termination dashed lines for FB_CS, FB_BE/BWE, and FB_OE signals.
Figure 17-31/Page 17-26	Remove internal termination dashed lines for FB_CS, FB_BE/BWE, and FB_OE signals.
Figure 17-33/Page 17-27	Remove internal termination dashed lines for FB_CS, FB_BE/BWE, and FB_OE signals.
Chapter 18	Only one SD_CS signal is available on this device. Remove mention of two chip selects throughout.
Table 18-1/Page 18-5	In the SD_DQS table entry add the following note: Note: If a read is attempted from a DDR SDRAM chip select when there is no memory to respond with the appropriate SD_DQS pulses, then the bus cycle will hang. Since there is no high level bus monitor on the device, a reset is the only way to exit this error condition.
Figure 18-2/Page 18-11	Replace figure with Figure 1 from AN2982 "System Design Using the ColdFire MCF5208 Split Bus Architecture" found at http://www.freescale.com/coldfire since it is more thorough.
Figure 18-2/Page 18-12	SD_D[31:0], DQ[31:0], SD_DQS[3:0], and DQS[3:0] should be SD_D[31:16], DQ[31:16], SD_DQS[3:2], and DQS[3:2], respectively, as the device does not support a 32-bit DDR bus. Replace figure with Figure 2 from AN2982 "System Design Using the ColdFire MCF5208 Split Bus Architecture" found at http://www.freescale.com/coldfire since it is more thorough.
Section 18.3.5/Page 18-13	Remove this entire section, as the device does not support a 32-bit wide DDR bus.
Table 18-8/Page 18-17	DQS_OE field should match the corresponding register diagram and be only 2 bits wide at locations 11–10. Change third sentence from "The DSQ_OE[3] bit enables SD_DQS3 and the DSQ_OE[2] bit enables SD_DQS2, and so on." to ""The DSQ_OE[1] bit enables SD_DQS3 and the DSQ_OE[0] bit enables SD_DQS2." Consequently, the reserved bit field currently at location 7–3 should be extended to bits 9–3.
Table 18-9/Page 18-19	Correct equations and examples in SDCFG1[ACT2RW, PRE2ACT, REF2ACT] fied descriptions. Change ACT2RW to the following and change PRE2ACT and REF2ACT similarly. "Suggested value = (t _{RCD} x f _{SD CLK}) - 1 (Round up to nearest integer)
	Example: If t _{RCD} = 20ns and f _{SD_CLK} = 99 MHz Suggested value = (20ns x 99 MHz) - 1 = 0.98; round to 1."



Table 1. MCF5373RM Rev 1 Errata (continued)

Location	Description							
Section 18.4.5/Page 18-20	Add the following note: NOTE The user should not probe memory on a DDR chip select to determine if memory is connected. If a read is attempted from a DDR SDRAM chip select when there is no memory to respond with the appropriate DQS pulses, then the bus cycle will hang. Since there is no high level bus monitor on the device, a reset is the only way to exit the error condition.							
Table 19-2/Page 19-6	Correct MIB block co	unte	rs end address to 0xFC03_02FF.					
Table 19-3/Page 19-6	Correct ECR reset va	lue	from 0xF000_0002 to 0xF000_0000.					
Table 19-3/Page 19-7			o in FEC memory map at address 0xFC03_0124. This should be the Address Register (GALR).					
Table 19-4/Page 19-8			the MIB counter memory map at address 0xFC03_0280 with a ames not counted correctly.'					
Figure 19-6/Page 19-13	Correct ECR reset va	lue 1	from 0xF000_0002 to 0xF000_0000.					
Section 19.4.7/Page 19-35	Add the following subsection entitled "Duplicate Frame Transmission": The FEC fetches transmit buffer descriptors (TxBDs) and the corresponding transmit data continuously until the transmit FIFO is full. It does not determine whether the TxBD to be fetched is already being processed internally (as a result of a wrap). As the FEC nears the end of the transmission of one frame, it begins to DMA the data for the next frame. In order to remain one BD ahead of the DMA, it also fetches the TxBD for the next frame. It is possible that the FEC will fetch from memory a BD that has already been processed but not yet written back (that is, it is read a second time with the R bit still set). In this case, the data is fetched and transmitted again. Using at least three TxBDs fixes this problem for large frames, but not for small frames. To ensure correct operation for either large or small frames, one of the following must be true: • The FEC software driver ensures that there is always at least one TxBD with the ready bit cleared. • Every frame uses more than one TxBD and every TxBD but the last is written back immediately after the data is fetched. • The FEC software driver ensures a minimum frame size, <i>n</i> . The minimum number of TxBDs is then (Tx FIFO Size ÷ (<i>n</i> + 4)) rounded up to the nearest integer (though the result cannot be less than three). The default Tx FIFO size is 192 bytes; this size is programmable.							
Table 21-2/Page 21-6	Change USBOTG_P	U_E	N entry to the following.					
	Signal	I/O	Description					
	USBOTG_PU_EN	0	Enables an external pull-up on the USBOTG_DP line. This signal is controlled by the UOCSR[BVLD] bit.					
			State Asserted—Pull-up enabled. UOCSR[BVLD] set. Meaning Negated—Pull-up disabled. UOCSR[BVLD] cleared.					
	Timing Asynchronous							
Section 21.3.3.1/Page 21-18	Move USBCMD[ATDTW] from bit location 14 to 12 in both the register figure and bit description table. Bit 14 is reserved and must be cleared.							
Table 21-19/Page 21-23	Delete last sentence in UEI bit description. Add the following sentence to the end of the PCI bit description: "The device controller detects resume signaling only."							



Location	Description
Table 21-43/Page 21-49	Change ZLT bit description to the following: "Zero length termination select. This bit is ignored in isochronous transfers. Clearing this bit enables the hardware to automatically append a zero length packet when the following conditions are true: • The packet transmitted equals maximum packet length • The dTD has exhausted the field Total Bytes After this the dTD will be retired. When the device is receiving, if the last packet length received equals the maximum packet length and the total bytes is zero, it will wait for a zero length packet from the host to retire the current dTD. Setting this bit disables the zero length packet. When the device is transmitting, the hardware will not append any zero length packet. When receiving, it will not require a zero length packet to retire a dTD whose last packet was equal to the maximum packet length packet. The dTD is retired as soon as Total Bytes field goes to zero, or a short packet is received. 0 Enable zero length packet (default). 1 Disable the zero length packet. Note: Each transfer is defined by one dTD, so the zero length termination is for each dTD. In some software application cases, the logic transfer does not fit into just one dTD, so it does not make sense to add a zero length termination packet each time a dTD is consumed. On those cases we recommend to disable the ZLT feature, and use software to generate the zero length termination."
Chapter 23	Rescind errata regarding 2HZ/2SEC bitfield name. The interrupt is, in fact, a 2 Hz interrupt.
Figure 22-15/Page 22-15	Correct register name in top of register figure from SISRR to SSI_ISR.
Figure 22-18/Page 22-20	Add R/W RXDIR bit to bit location 5 in SSI_RCR register.
Table 22-11/Page 22-21	Add RXDIR bit to bit location 5 with the following description: Gated clock enable. In synchronous mode, this bit enables gated clock mode. Gated clock mode disabled. Gated clock mode enabled.
Section 24.2/Page 24-2	Previous errata from revision 0 has crept in: Add a 0x20 offset to all PWM register addresses in the memory map table. Register addresses should be from 0xFC09_0020 to 0xFC09_0044. Also fix address for the PWMSDN register description to 0xFC09_0044.
Figure 25-1/Page 25-2	Change 8192 divider to 4096.
Section 25.2.3/Page 25-4	Change 8192 multiplier in equation 20-1 and text below it to 4096. As a result the maximum timeout frequency changes from 6.71 to 3.36 seconds.
Figure 26-4/Page 26-5	Remove "IPSBAR Offset" from PCNTRn register diagram.
Section 29.2 / Page 29-3	Changed "An internal interrupt request signal notifies the interrupt controller" to "A request signal is provided to notify the interrupt controller".
Table 29-6 / Page 29-9	Changed "DTIN" to "DTnIN" (to maintain consistent signal names throughout chapter).
Section 29.4.5.2 / Page 29-26	Changed "complete normally without exception processing" to "complete normally without an error termination".
Figure 35-3/Page 35-4	Updated the IDCODE register figure to indicate that the reset values for both PRN and PIN are device-dependent.



2 Errata for Revision 0.1

Table 2. MCF5373RM Rev 0.1 Errata

Location	Description									
Throughout	Remove any m	Remove any mention of ULPI from manual, as it is not supported on this device.								
Table 2-1/Page 2-1	Change the pin	Change the pin number for signal A10 in the 160 QFP packaging from 11 to 117.								
Table 2-1/Page 2-2		omain" column ir FlexBus and SDF			•					
Table 2-1/Page 2-2	signals: The SDRAM fu	ng footnote to the nctions of these processor when	signals are not p	oro	grammable by th	ne user. They				
Figure 2-1/Page 2-2	device.	signals as alterna iPIO signal name		n t	he FEC pins. UL	PI is not supp				
		Orig	jinal		Corrected					
		Signal Name GPIO			Signal Name	GPIO				
		FEC_COL	PFECH4		FEC_COL	PFECH7				
		FEC_CRS	PFECH0		FEC_CRS	PFECH6				
		FEC_RXCLK	PFECH3		FEC_RXCLK	PFECH5				
		FEC_RXDV	PFECH2		FEC_RXDV	PFECH4				
		FEC_RXD[3:1]	PFECL[3:1]		FEC_RXD[3:0]	PFECH[3:0]				
		FEC_RXD0	PFECH1							
		FEC_RXER	PFECL0		FEC_RXER	PFECL7				
		FEC_TXCLK	PFECL7		FEC_TXCLK	PFECL6				
		FEC_TXEN	PFECL6		FEC_TXEN	PFECL5				
		FEC_TXER	PFECL4		FEC_TXER	PFECL4				
		FEC_TXD[3:1]	PFECL[7:5]		FEC_TXD[3:0]	PFECL[3:0]				
		FEC_TXD0	PFECH5							



Location	Description									
Table 2-1/Page 2-6	as these are	ate functions of the reserved. PIO signal name		сер	t for the FEC_M	DC and FEC_	MDIO signals),			
		Orig	inal		Correc	ted				
		Signal Name	GPIO		Signal Name	GPIO				
		FEC_COL	PFECH4		FEC_COL	PFECH7				
		FEC_CRS	PFECH0		FEC_CRS	PFECH6				
		FEC_RXCLK	PFECH3		FEC_RXCLK	PFECH5				
		FEC_RXDV	PFECH2		FEC_RXDV	PFECH4				
		FEC_RXD[3:1]	PFECL[3:1]		FEC_RXD[3:0]	PFECH[3:0]				
		FEC_RXD0	PFECH1							
		FEC_RXER	PFECL0		FEC_RXER	PFECL7				
		FEC_TXCLK	PFECL7		FEC_TXCLK	PFECL6				
		FEC_TXEN	PFECL6		FEC_TXEN	PFECL5				
		FEC_TXER	PFECL4		FEC_TXER	PFECL4				
		FEC_TXD[3:1]	PFECL[7:5]		FEC_TXD[3:0]	PFECL[3:0]				
		FEC_TXD0	PFECH5							
Table 2-1/Page 2-7	Change USBH	OST_VSS entry	to USB_VSS an	nd L	JSBOTG_VDD (entry to USB_	VDD.			
Table 2-6/Page 2-10		tion of the BE/BV Remove SDRAM					sentence of first			
Table 2-7/Page 2-11	Add the following to the SD_DQM[3:0] entry description: "These pins are multiplexed with the BE/BWEn pins. The SD_DQMn should be connected to individual SDRAM DQM signals. Note that most SDRAMs associate DQM3 with the MSB, in which case SD_DQM3 should be connected to the SDRAM's DQM3 input."									
Section 3.2.5/Page 3-7	•	Change bit 7 of the CCR register from a reserved bit to a read/write bit labeled 'P'. In corresponding bit description table, add a row for the P bit with the below description:								
	Branch prediction bit. Alters the static prediction algorithm used by the branch acceleration logic in the IFP on forward conditional branches. O Predicted as not taken. 1 Predicted as taken.									
Figure 3-9/Page 3-10	Change bit 7 fro	om a reserved bi	t to a read/write	bit	labeled 'P'.					
Figure 5.2/Page 5-2	Change TAG de	efinition label fror	n "TAG—21-bit	ado	dress tag" to "TA	G—20-bit add	lress tag".			



Table 2. MCF5373RM Rev 0.1 Errata (continued)

Location	Description								
Table 9-10/Page 9-10	Correct boot port size (D[4:3]) settings. They should match Table 9-3.								
	D[4:3] Boot Device								
	00 External with 32-bit port ³ (default)								
		01 External with 16-bit port							
		10 External with 8-bit port							
		11	External with 32-bit port]					
Table 11-1/Page 11-2	Change reset values of MPR0 to 0x7777_7777. Change reset value of PACRA to 0x5444_4444. Change reset values of the other PACRs to 0x4444_4444. Change CFDTR register address from 0xFC04_0078 to 0xFC04_007C.								
Figure 11-1/Page 11-3	Change reset value of MPR0 from 0x7000_0007 to 0x7777_7777.								
Section 11.2.3/Page 11-4	Change reset values of PACRA to 0x5444_4444 and of the rest of the PACRs to 0x4444_4444.								
Section 11.2.4/Page 11-7	Change next to last sentence in second paragraph from "an interrupt to the interrupt controller is generated if the CFLOC[ECFEI] bit is set." to ""an interrupt to the interrupt controller is generated if the CFIER								
Section 11.2.8/Page 11-10	Change last sentence in first paragraph from "There is a enable bit" to "There is an enable bit"								
Figure 11-22/Page 11-14	Change CFDTR reg	gister address fro	om 0xFC04_0078 to 0xFC04_007C.						



Location	Description									
Table 12-1/Page 12-2	For the slave modules add a column for each slave's address range, as well as two footnotes as shown below:									
	Table 12-1. Cross-bar Switch Master/Slave Assignments									
	Master Modules									
	Cross-bar Port	М	odule							
	Master 0 (M0)	Cold	Fire Core							
	Master 1 (M1)	eDMA	Controller							
	Master 2 (M2)	Fast Ethe	rnet Controller							
	Master 4 (M4)	Re	served							
	Master 5 (M5)	US	B Host							
	Master 6 (M6)	USB	On-the-Go							
	Master 7 (M7)	Reserved t	or Factory Test							
		Slave Modules								
	Cross-bar Port	Module	Address Range ¹							
	Slave 1 (S1)	Flexbus SDRAM Controller	0x0000_0000-0x3FFF_FFFF & 0xC000_0000-0xDFFF_FFFF							
	Slave 4 (S4)	Internal SRAM Backdoor	0x8000_0000-0x8FFF_FFFF							
	Slave 6 (S6)	Cryptography Modules (RNG, SKHA, MDHA)	0xE000_0000-0xEFFF_FFFF ²							
	Slave 7 (S7)	Other On-chip Peripherals	0xF000_0000-0xFFFF_FFFF ²							
		heral chapters for their memory	maps. Any unused space by ed and should not be accessed.							
Section 12.1/Page 12-2	Add the following note below									
	This memory map provides two disjoint regions mapped to the FlexBus controller to support glueless connections to external memories (e.g., flash and SRAM) as well as a second space with one (or more) unique chip-selects that can be used for non-cacheable, non-memory devices (addresses 0xC000_0000-0xDFFF_FFFF). Additionally, this mapping is selected since it easily maps into the ColdFire access control registers, which provide a coarse association between memory addresses and their attributes (e.g., cacheable, non-cacheable). For this device, one possible configuration defines the default memory attribute as non-chacheable, and one ACR is then used to identify cacheable addresses, e.g., ADDR[31]=0 identifies the cacheable space.									
attribute as non-chacheable, and one ACR is then used to identify cacheable addresses, e.g., ADDR[31]=0 identifies the cacheable										

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Table 2. MCF5373RM Rev 0.1 Errata (continued)

Location	Description								
Table 13-1/Page 13-2	Add "Voltage Domain" column indicated the domain for each signal. The USB signals are USB_VDD, FlexBus and SDRAM signals are SD_VDD, while all the rest are EVDD.								
Table 13-1/Page 13-2	signals: The SDRAM fu	Add the following footnote to the SD_BA[1:0], SD_A[13:11], SD_A[9:0], and SD_DQM[3:0] signals: The SDRAM functions of these signals are not programmable by the user. They are dynamically switched by the processor when accessing SDRAM memory space and are included here for							
Figure 13-1/Page 13-2	device.	signals as alterna iPIO signal name		n t	he FEC pins. UL	PI is not supp			
		Orig	inal		Correc	cted			
		Signal Name	GPIO		Signal Name	GPIO			
		FEC_COL PFECH4			FEC_COL	PFECH7			
		FEC_CRS	PFECH0		FEC_CRS	PFECH6			
		FEC_RXCLK	PFECH3		FEC_RXCLK	PFECH5			
		FEC_RXDV	PFECH2		FEC_RXDV	PFECH4			
		FEC_RXD[3:1]	PFECL[3:1]		FEC_RXD[3:0]	PFECH[3:0]			
		FEC_RXD0	PFECH1						
		FEC_RXER	PFECL0		FEC_RXER	PFECL7			
		FEC_TXCLK	PFECL7		FEC_TXCLK	PFECL6			
		FEC_TXEN	PFECL6		FEC_TXEN	PFECL5			
		FEC_TXER PFECL4 FEC_TXER PFECL4							
		FEC_TXD[3:1]	PFECL[7:5]		FEC_TXD[3:0]	PFECL[3:0]			
		FEC_TXD0	PFECH5	1					



Location	Description										
Table 13-1/Page 13-6	Remove alternate functions of the FEC pins (except for the FEC_MDC and FEC_MDIO signals), as these are reserved. Change FEC GPIO signal names:										
		Original Corrected									
		Signa	I Name	GF	PIO	Sig	ınal Name	G	PIO		
		FEC.	_COL	PFE	CH4	F	EC_COL	PFE	ECH7		
		FEC.	_CRS	PFE	CH0	F	EC_CRS	PFE	ECH6		
		FEC_F	RXCLK	PFE	СНЗ	FE	C_RXCLK	PFE	ECH5		
		FEC_	RXDV	PFE	CH2	FE	EC_RXDV	PFE	ECH4		
		FEC_R	RXD[3:1]	PFEC	L[3:1]	FE	C_RXD[3:0]	PFEC	CH[3:0]		
		FEC_	RXD0	PFE	CH1						
		FEC_	RXER	PFE	CL0	FE	EC_RXER	PF	ECL7		
		FEC_	TXCLK	PFE	CL7	FE	C_TXCLK	PFECL6			
			TXEN		CL6		EC_TXEN		ECL5		
			TXER		CL4	-	EC_TXER	PFECL4			
			XD[3:1]	PFECL[7:5]		FE	FEC_TXD[3:0]		PFECL[3:0]		
		FEC_	FEC_TXD0		CH5						
Table 13-1/Page 13-10	Change USBH	OST_VS	SS entry	to USB_	VSS and	USB	OTG_VDD (entry t	o USB_	VDD.	
Table 13-3/Page 13-9	Correct the var	ious FE0	C GPIO r	egister a	addresse	S.					
			Regi	ster	Origi Addr		Correct Addres				
			PODR_	FECH	0xFC0A	_4000	_4000				
			PODR_	_FECL	0xFC0A	_4001		100F			
			PDDR_		0xFC0A	A_4014 0xFC0A_					
			PDDR_		0xFC0A						
			PPDSDF		0xFC0A		0xFC0A_4				
			PPDSDR_FECL PCLRR_FECH		0xFC0A_4029 0xFC0A_403C		0xFC0A_4037 0xFC0A_404A				
			PCLRR_FECL		0xFC0A_403D		0xFC0A_404B				
			_		0xFC0A_4050		0xFC0A_4				
Figure 13-3/Page 13-12	Correct PODR_ Correct PODR_										
Figure 13-9/Page 13-14	Correct PDDR_ Correct PDDR_										



Table 2. MCF5373RM Rev 0.1 Errata (continued)

Location	Description							
Figure 13-15/Page 13-16	Correct PPDSDR_FECH register address to 0xFC0A_4036. Correct PPDSDR_FECL register address to 0xFC0A_4037.							
Figure 13-21/Page 13-18	Correct PCLRR_FECH register address to 0xFC0A_404A. Correct PCLRR_FECL register address to 0xFC0A_404B.							
Figure 13-33/Page 13-23	Correct PAR_FECH register address to 0xFC0A_405D. Change PAR_FEC_7W to a one-bit field at bit number 3. Change PAR_FEC_MII to a one-bit field at bit number 1.							
Table 13-15/Page 13-24	Change PAR_FEC_7W to a one-bit field at bit number 3. Change PAR_FEC_7W bit description to: "FEC 7-wire pin assignment. These bit fields configure the FEC_COL, FEC_RXCLK, FEC_RXDV, FEC_RXD0, FEC_TXCLK, FEC_TXD0, and FEC_TXEN pins for their primary FEC function or GPIO. 0 Above pins configured as GPIO. 1 Above pins configured as FEC."							
Table 13-15/Page 13-24	Change PAR_FEC_MII to a one-bit field at bit number 1. Change PAR_FEC_MII bit description to: "FEC MII pin assignment. These bit fields configure the FEC_CRS, FEC_RXD3, FEC_RXD2, FEC_RXD1, FEC_RXER, FEC_TXD3, FEC_TXD2, FEC_TXD1 and FEC_TXER pins for their primary FEC function or GPIO. O Above pins configured as GPIO. Above pins configured as FEC."							
Figure 13-28/Page 13-20	Change figure title to "Chip Select Pin Assignment Register (PAR_CS)"							
Table 13-10/Page 13-20	Correct table title to "PAR_CS Field Descriptions" Correct bit field names for bit 5 and bit 4. Bit 5 field should be PAR_CS5 and bit field 4 should be PAR_CS4. The corresponding bit descriptions are correct.							
Table 14-15/Page 14-12	Correct source #25, "Flag clearing mechanism" entry from "Write CWIR[CWIC]=1" to "Write SCMISR[CWIC]=1".							
Figure 15-3/Page 15-4	Change register diagram from 16-bit to 8-bit as shown below:							
	Address: 0xFC09_4002 (EPDDR) Access: Supervisor read/write							
	7 6 5 4 3 2 1 0							
	R W EPDD7 EPDD6 EPDD5 EPDD4 EPDD3 EPDD2 EPDD1 0							
	Reset 0 0 0 0 0 0 0 0							
	Figure 15-3. EPORT Data Direction Register (EPDDR)							
Throughout Chapter 17	In all timing diagrams within the FlexBus chapter, the address and data signals stop driving the bus one clock cycle sooner than shown. Because of this, in the diagrams illustrating address hold, the address hold state is swapped with the S3 state.							
Figure 17-28/Page 17-23	Insert a single clock cycle for address setup at the beginning of each data transfer, between S0 and S1 states.							
Figure 17-29/Page 17-24	Insert a single clock cycle for address setup at the beginning of each data transfer, between S0 and S1 states.							
Section 18.5.2/Page 18-23	Remove "Perform a single read/write to any of the SDRAM chip select address spaces to issue the command." sentence from steps 5 and 9 of Section 18.6, "Initialization/Application Information." This is not recommended or necessary.							

MCF5373 Reference Manual Errata, Rev. 1.3



Location	Description
Table 19-2/Page 19-5	Change reset value of ECR register from 0x0000_0000 to 0xF000_0002.
Section 19.2.3/Page 19-6	Change second sentence in first paragraph from "These fall in the 0xFC03_0200-0xFC03_03FF address offset range." to "These fall in the 0xFC03_0200-0xFC03_02FF address range."
Figure 19-6/Page 19-12	Change reset value of ECR register from 0x0000_0000 to 0xF000_0002.
Table 19-11/Page 19-15	Change 80MHz entry for MSCR[MII_SPEED] from 0xF to 0x10.
Section 21.3.3.15/Page 21-37	Change bit 2 in the USBMODE register from a reserved bit to a read/write bit labeled 'ES'. In corresponding bit description table, change bit 2 to the ES bit with the below description: Endian select. Controls the byte ordering of the transfer buffers to match the host microprocessor bus architecture. The bit fields in the register interface and the DMA data structures (including the setup buffer within the device QH) are unaffected by the value of this bit, because they are based upon 32-bit words. 0 Little endian. First byte referenced in least significant byte of 32-bit word.
	For proper operation, this bit must be set for this ColdFire device.
Table 34-5/Page 34-8	Clarify in CSR field descriptions that the read-only bits can only be accessed via the BDM port and not read via the processor. The CSR is supervisor write-only from the processor.



3 Errata for Revision 0

Table 3. MCF5373RM Rev 0 Errata

Location				Description	
Table 2-2/Page 2-7	Replace the	Replace the table with the following. Notice the addition of the D0 entry: Table 2-2. Internal Pull-up/down Resistors			
	Pin Name	Pull-Up	Pull-Down	Comment	
	RESET	х		Always, except JTAG mode	
	TEST		х	Always, except JTAG mode	
	RCON	х		Always, except JTAG mode	
	XTAL	х		When not in crystal oscillator mode (intended for factory test)	
	IRQ[7:1]	х			
	TA	х		Only when used as TA	
	D0	х		During reset only	
	QSPI_DOUT	х		I ² C mode only (I2C_SDA)	
	QSPI_CLK	х		I ² C mode only (I2C_SCL)	
	FEC_MDIO	х		I ² C mode only (I2C_SDA)	
	FEC_MDC	х		I ² C mode only (I2C_SCL)	
	I2C_SDA	х		I ² C mode only (I2C_SDA)	
	I2C_SCL	х		I ² C mode only (I2C_SCL)	
	DT0IN	х		When used as DREQ0	
	U1RXD	х	х	When used as SSI_RXD, configured by the MISCCR register in the CCM	
	U1TXD	х	х	When used as SSI_TXD, configured by the MISCCR register in the CCM	
	JTAG_EN		х		
	TDI	х		JTAG mode only	
	TMS	х		JTAG mode only	
	TRST	х		JTAG mode only	
	TCLK	Х		JTAG mode only	
Section 5.2.1/Page 5.4	Change CAC	D bit 4	from rocars	and to EUSP in register figure and hit description table. Add the	
Section 5.3.1/Page 5-4	following for Enable user	EUSP's stack po	bit descrip ointer. See	ved to EUSP in register figure and bit description table. Add the tion: Section 3.2.3, "Supervisor/User Stack Pointers (A7 and tion on the dual stack pointer implementation.	
	0 Disable th	e proces	ssor's use	of the User Stack Pointer of the User Stack Pointer of the User Stack Pointer	



Location	Description
Section 5.4.4/Page 5-12	Change last sentence from: "Therefore, on-chip DMA channels cannot access local memory and do not maintain coherency with the unified cache." to: "Therefore, on-chip DMA channels should not access cached local memory locations, as coherency is not maintained with the unified cache."
Section 5.5/Page 5-16	Remove cache code examples from section, as they are incorrect. Cache code examples can be found within sample projects in the 'MCF532XSC.ZIP' file available at the device web site at http://www.freescale.com/coldfire
Table 6-1/Page 6-2	Remove '1' from RAMBAR register name and mnemonic.
Section 6.2.1/Page 6-2	Add the following two notes:
	Note: By default the RAMBAR is invalid, but the back door is enabled. In this state, any core accesses to the SRAM will be routed through the backdoor. Therefore the SRAM is accessible by the core, but it will not have a single-cycle access time. In order to insure that the core will have single-cycle access to the SRAM, the RAMBAR[V] bit should be set.
	Note: Any access within the memory range allocated for the on-chip SRAM (0x8000_0000-0x8FFF_FFFF) will "hit" in the SRAM even if the address is beyond the defined size for the SRAM. This creates a ghosting effect for the on-chip SRAM memory. For example, writes to addresses 0x8000_0000 and 0x8000_8000 will actually modify the exact same memory location. System software should ensure that SRAM address pointers do not exceed the size of the SRAM in order to prevent unwanted overwriting of SRAM.
Figure 6-1/Page 6-2	Change the reset value for the RAMBAR[BDE] bit from 0 to 1.
Table 11-1/Page 11-2	Correct BCR register address from 0xFC04_002A to 0xFC04_0024.
Figure 11-17/Page 11-10	Correct BCR register address from 0xFC04_002A to 0xFC04_0024.
Chapter 12	Add reserved masters used only for factory test purposes at location M4 and M7. The XBS_PRSn[M4,M7] fields must comply with the restriction that their value must be unique to the other Mn fields.
Section 12.4.1/Page 12-4	The possible values for the XBS_PRSn fields depend on the number of masters available on the device. Since the device contains seven masters (including reserved masters) then valid values are '000' to '110'. Unpredictable results will occur when using the reserved 111 setting. Update reset values accordingly to 0x6543_0210.
Table 13-1/Page 13-4	Update footnotes in table to correspond to corrections in Table 2-2 as indicated above.
Table 13-14/Page 13-23	In the bit descriptions for the PAR_U0CTS and PAR_U0RTS bits, the description for the bit being set incorrectly refers to UART1 while it should refer to the UART0 port.
Section 17.3.1.1/Page 17-4	Change next to last sentence in section to "For example, a 16-bit address/16-bit data device would connect its addr[15:0] to A[16:1] and data[15:0] to D[31:16]."
Section 17.4.2/Page 17-9	Change the end of the first sentence of the second paragraph from: "if a longword is transferred for three port sizes when not in split but mode." to "if a longword is transferred for three port sizes when not in split bus mode."
Figure 19-24/Page 19-23	Correct EMRBR register address from 0xFC03_01B8 to 0xFC03_0188
Section 21.1.3/Page 21-4	Add the following sub-bullet under the "USB device mode" bullet: — Supports full-speed operation via the on-chip transceiver and FS/HS operation using an external ULPI transceiver



Revision History

Table 3. MCF5373RM Rev 0 Errata (continued)

Location	Description
Section 21.1.3/Page 21-5	Change the following sub-bullet: "External ULPI transceiver supports high speed (480 Mbps), full speed, and low speed" to — External ULPI transceiver supports high-speed (480 Mbps), full-speed, and low-speed operation in host mode and high-speed and full-speed operation in device mode.
Table 21-40/Page 21-45	Change "USB Device FS/LS" entry to "USB Device FS". Change "Host/Device ULPI HS/FS/LS" to "Host/Device ULPI HS/FS".
Section 21.4.4.1/Page 21-45	In the note, change the second sentence of the second paragraph from "Device operation requires a $1.5 \mathrm{k}\Omega$ pull-up resistor on either DP (full-speed operation) or DN (low-speed operation) ports." to "Device operation requires a $1.5 \mathrm{k}\Omega$ pull-up resistor on DP (full-speed operation)." since low-speed operation is not supported in device mode.
Section 23.3/Page 23-3	Add 0xFC0A_0800 to each register address.
Section 23.3.6/Page 23-6	Change RTC_ISR[2HZ] bit field name to 2SEC as it more accurately describes the bit definition.
Section 23.3.7/Page 23-7	Change RTC_IER[2HZ] bit field name to 2SEC as it more accurately describes the bit definition.
Section 24.2/Page 24-2	Add a 0x20 offset to all PWM register addresses throughout section. Register addresses should be from 0xFC09_0020 to 0xFC09_0044.
Table 34-21/Page 34-35	Remove '1' from RAMBAR register name and mnemonic.

4 Revision History

Table 4 provides a revision history for this document.

Table 4. Revision History Table

Rev. Number	Substantive Changes	Date of Release			
	The below errata were added for MCF5373RM Revision 0				
0	Initial release. • Added "Signal Descriptions" chapter errata. • Added cache coherency section errata. • Added RAMBAR section errata. • Added RAMBAR[BDE] reset value errata. • Added BCR register address errata. • Added internal pull-up/down corrections. • Added PAR_UOCTS & PAR_UORTS bit description errata. • Added Flexbus typo regarding split bus mode.	12/2005			
0.1	Added USB OTG chapter errata regarding device mode not supporting low-speed operation.	12/2005			
0.2	 Added CACR[EUSP] bit errata. Added PWM register address errata. Added FEC EMRBR address errata. Added cross-bar reserved masters and restriction on the Mn bit field settings. Added RTC_IxR[2HZ] bit name errata. Added RTC register address errata. Added Flexbus 16-bit address connection example errata. Added FlexCAN IMASK register address errata and register suffix errata. Added RAMBAR1 errata in SRAM and Debug chapters. 	02/2006			

MCF5373 Reference Manual Errata, Rev. 1.3



Table 4. Revision History Table (continued)

Rev. Number	Substantive Changes	Date of Release		
The below errata were added for MCF5373RM Revision 0.1				
0.3	Added CCR[P] bit errata. Added USBMODE[ES] bit errata.	02/2006		
0.4	Added BE/BWEn and SD_DQMn signal description errata. Added edge port EPDDR register figure errata. Added FEC MSCR programming example table errata. Added FEC ECR register reset value. Added cache code example errata.	02/2006		
0.5	 Added PAR_CS[5,4] field name and figure/table title errata. Added FEC MIB memory map address range errata. Added TAG description labe errata in cache chapter. Added CFLOC-> CFIER register errata in SCM chapter. Added typo in BCR section in SCM chapter. Added flag clearing mechanism errata for source #25 in interrupt source table. Added CFDTR register address errata. Added boot port size errata. Added CSR read-only clarification. Added FlexCAN wake-up interrupt source errata. 	03/2006		
0.6	 Added GPIO signal name assignment errata for FEC pins. Added ULPI errata. Added MPR0 reset value errata. Added Flexbus burst-inhibited transfer timing diagram errata. 	05/2006		
0.7	 Added 160QFP A10 signal pin location errata. Added voltage domain column, USB_VDD/USB_VSS name change errata, and SDRAM signal footnotes to pin-muxing table. Added crossbar switch slave address range errata. Added FlexBus diagrams errata regarding address & data lines. Added SDRAM initialization sequence errata regarding PALL command. 	07/2006		
	The below errata were added for MCF5373RM Revision 1			
1	Added notes regarding SDRAM bus hanging if the memory does not respond with appropriate DQS pulses. Added five SDRAM chapter errata regarding 32-bit DDR bus.	08/2006		
1.1	 Added PCNTRn register diagram errata. Added D[31:0] direction errata in Table 2-1 and Table 13-1. Added note to LPCR[FWKUP] bit. Added CDR[SSIDIV] field width errata. Added SSI_ISR register mnemonic errata. Rescinded errata regarding 2HZ/2SEC bitfield name. Added cache lock errata. 	10/2006		



Revision History

Table 4. Revision History Table (continued)

Rev. Number	Substantive Changes	Date of Release
1.2	Added SSI_RCR[RXDIR] errata. Added RMON_R_DROP counter in FEC MIB counters memory map. Added ADDR[31:0] label on FlexBus figures and note explaining this clock cycle. Added PWM memory map errata.	11/2006
1.3	 Added various core, EMAC, cache, RAMBAR, and debug chapters errata. Added SCM's BCR errata. Added 2 FEC memory map typos. Added FEC ECR reset value errata. Added watchdog timer multiplier errata. Added "Duplicate Frame Transmission" section to FEC chapter. Added internal termination figure errata for longword write bursts. Added USBOTG_PU_EN signal description errata. Added USBCMD[ATDTW] errata. Added USBSTS[UEI,PCI] and ZLT bit description errata. Added SDCFG1 field description errata. Added various UART errata. Updated the IDCODE register figure to indicate that the reset values for both PRN and PIN are device-dependent. Added SDCFG1 field description errata. Added SDCFG1 field description errata. Added SDRAM chip select errata. 	05/2007



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